

Welcome to [E-XFL.COM](https://www.e-xfl.com)

### Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### Applications of Embedded - CPLDs

#### Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	512
Number of Gates	10000
Number of I/O	212
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/epm7512aefc256-12">https://www.e-xfl.com/product-detail/intel/epm7512aefc256-12</a>

- Software design support and automatic place-and-route provided by Altera’s development systems for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations
- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, and VeriBest
- Programming support with Altera’s Master Programming Unit (MPU), MasterBlaster™ serial/universal serial bus (USB) communications cable, ByteBlasterMV™ parallel port download cable, and BitBlaster™ serial download cable, as well as programming hardware from third-party manufacturers and any Jam™ STAPL File (.jam), Jam Byte-Code File (.jbc), or Serial Vector Format File- (.svf) capable in-circuit tester

## General Description

MAX 7000A (including MAX 7000AE) devices are high-density, high-performance devices based on Altera’s second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000A devices operate with a 3.3-V supply voltage and provide 600 to 10,000 usable gates, ISP, pin-to-pin delays as fast as 4.5 ns, and counter speeds of up to 227.3 MHz. MAX 7000A devices in the -4, -5, -6, -7, and some -10 speed grades are compatible with the timing requirements for 33 MHz operation of the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2*. See [Table 2](#).

**Table 2. MAX 7000A Speed Grades**

Device	Speed Grade					
	-4	-5	-6	-7	-10	-12
EPM7032AE	✓			✓	✓	
EPM7064AE	✓			✓	✓	
EPM7128A			✓	✓	✓	✓
EPM7128AE		✓		✓	✓	
EPM7256A			✓	✓	✓	✓
EPM7256AE		✓		✓	✓	
EPM7512AE				✓	✓	✓

MAX 7000A devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000A architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000A devices contain from 32 to 512 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms, providing up to 32 product terms per macrocell.

MAX 7000A devices provide programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000A devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000A devices can be set for 2.5 V or 3.3 V, and all input pins are 2.5-V, 3.3-V, and 5.0-V tolerant, allowing MAX 7000A devices to be used in mixed-voltage systems.

MAX 7000A devices are supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2.0 and 3.0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

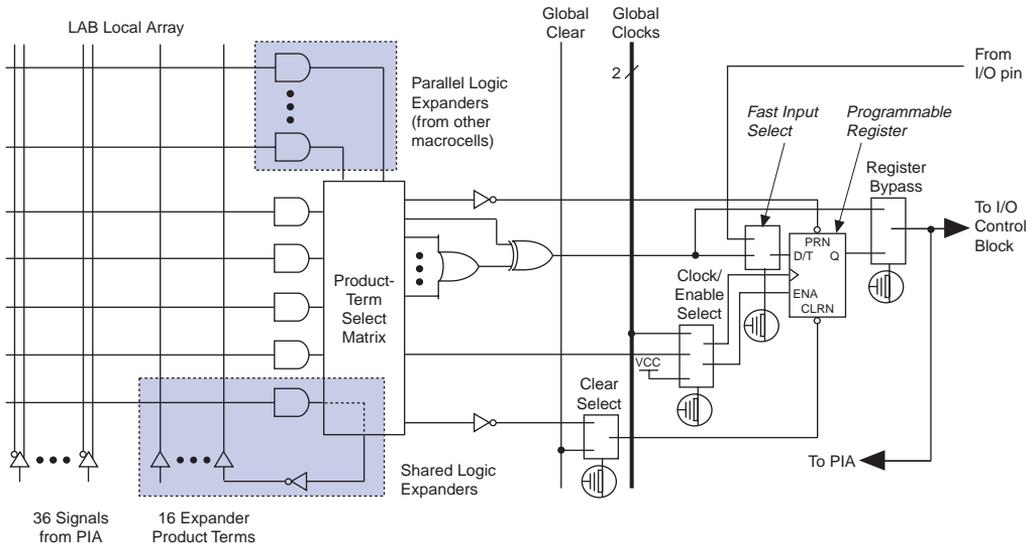


For more information on development tools, see the [MAX+PLUS II Programmable Logic Development System & Software Data Sheet](#) and the [Quartus Programmable Logic Development System & Software Data Sheet](#).

## Macrocells

MAX 7000A macrocells can be individually configured for either sequential or combinatorial logic operation. The macrocells consist of three functional blocks: the logic array, the product-term select matrix, and the programmable register. Figure 2 shows a MAX 7000A macrocell.

Figure 2. MAX 7000A Macrocell



Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register preset, clock, and clock enable control functions.

Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

## Expander Product Terms

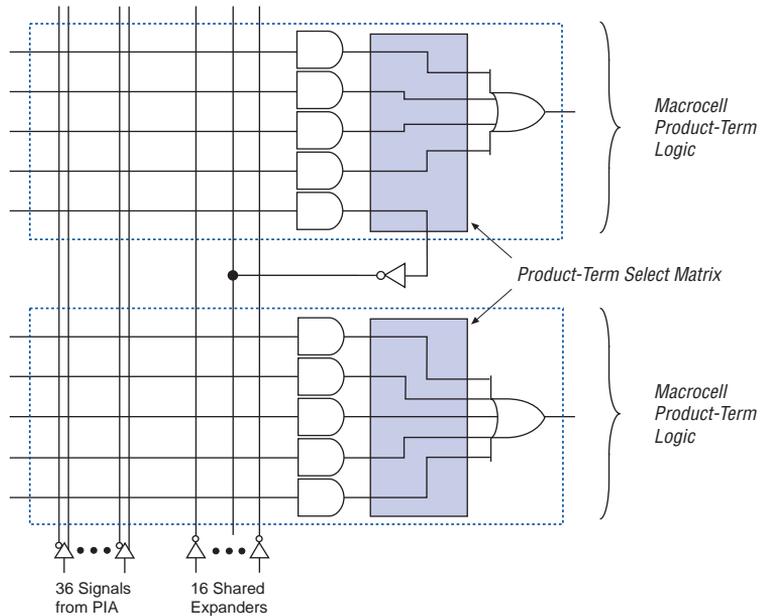
Although most logic functions can be implemented with the five product terms available in each macrocell, more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources. However, the MAX 7000A architecture also offers both shareable and parallel expander product terms that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

### Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay ( $t_{SEXP}$ ) is incurred when shareable expanders are used. Figure 3 shows how shareable expanders can feed multiple macrocells.

**Figure 3. MAX 7000A Shareable Expanders**

Shareable expanders can be shared by any or all macrocells in an LAB.



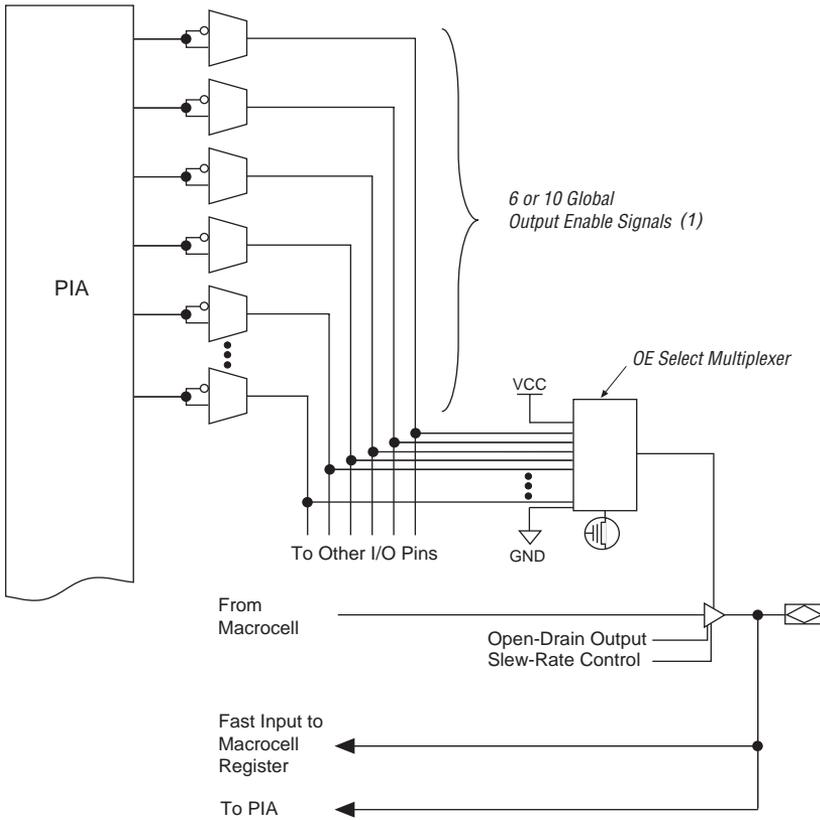
### *Parallel Expanders*

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with five product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

The compiler can allocate up to three sets of up to five parallel expanders to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay ( $t_{PEXP}$ ). For example, if a macrocell requires 14 product terms, the compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms, and the second set includes four product terms, increasing the total delay by  $2 \times t_{PEXP}$ .

Two groups of eight macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of eight, the lowest-numbered macrocell can only lend parallel expanders, and the highest-numbered macrocell can only borrow them. [Figure 4](#) shows how parallel expanders can be borrowed from a neighboring macrocell.

Figure 6. I/O Control Block of MAX 7000A Devices



**Note:**

- (1) EPM7032AE, EPM7064AE, EPM7128A, EPM7128AE, EPM7256A, and EPM7256AE devices have six output enable signals. EPM7512AE devices have 10 output enable signals.

When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to  $V_{CC}$ , the output is enabled.

The MAX 7000A architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

**Table 8. MAX 7000A JTAG Instructions**

JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins
BYPASS	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation
IDCODE	Selects the IDCODE register and places it between the TDI and TDO pins, allowing the IDCODE to be serially shifted out of TDO
USERCODE	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE value to be shifted out of TDO. The USERCODE instruction is available for MAX 7000AE devices only
UESCODE	These instructions select the user electronic signature (UESCODE) and allow the UESCODE to be shifted out of TDO. UESCODE instructions are available for EPM7128A and EPM7256A devices only.
ISP Instructions	These instructions are used when programming MAX 7000A devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, or BitBlaster download cable, or using a Jam STAPL File, JBC File, or SVF File via an embedded processor or test equipment.

The instruction register length of MAX 7000A devices is 10 bits. The user electronic signature (UES) register length in MAX 7000A devices is 16 bits. The MAX 7000AE USERCODE register length is 32 bits. Tables 9 and 10 show the boundary-scan register length and device IDCODE information for MAX 7000A devices.

**Table 9. MAX 7000A Boundary-Scan Register Length**

Device	Boundary-Scan Register Length
EPM7032AE	96
EPM7064AE	192
EPM7128A	288
EPM7128AE	288
EPM7256A	480
EPM7256AE	480
EPM7512AE	624

**Table 10. 32-Bit MAX 7000A Device IDCODE** *Note (1)*

Device	IDCODE (32 Bits)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)
EPM7032AE	0001	0111 0000 0011 0010	00001101110	1
EPM7064AE	0001	0111 0000 0110 0100	00001101110	1
EPM7128A	0000	0111 0001 0010 1000	00001101110	1
EPM7128AE	0001	0111 0001 0010 1000	00001101110	1
EPM7256A	0000	0111 0010 0101 0110	00001101110	1
EPM7256AE	0001	0111 0010 0101 0110	00001101110	1
EPM7512AE	0001	0111 0101 0001 0010	00001101110	1

**Notes:**

- (1) The most significant bit (MSB) is on the left.
- (2) The least significant bit (LSB) for all JTAG IDCODEs is 1.



See *Application Note 39 (IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices)* for more information on JTAG BST.

## Power Sequencing & Hot-Socketing

Because MAX 7000A devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. The  $V_{CCIO}$  and  $V_{CCINT}$  power planes can be powered in any order.

Signals can be driven into MAX 7000AE devices before and during power-up (and power-down) without damaging the device. Additionally, MAX 7000AE devices do not drive out during power-up. Once operating conditions are reached, MAX 7000AE devices operate as specified by the user.

MAX 7000AE device I/O pins will not source or sink more than 300  $\mu$ A of DC current during power-up. All pins can be driven up to 5.75 V during hot-socketing, except the  $OE1$  and  $GLCRn$  pins. The  $OE1$  and  $GLCRn$  pins can be driven up to 3.6 V during hot-socketing. After  $V_{CCINT}$  and  $V_{CCIO}$  reach the recommended operating conditions, these two pins are 5.0-V tolerant.

EPM7128A and EPM7256A devices do not support hot-socketing and may drive out during power-up.

## Design Security

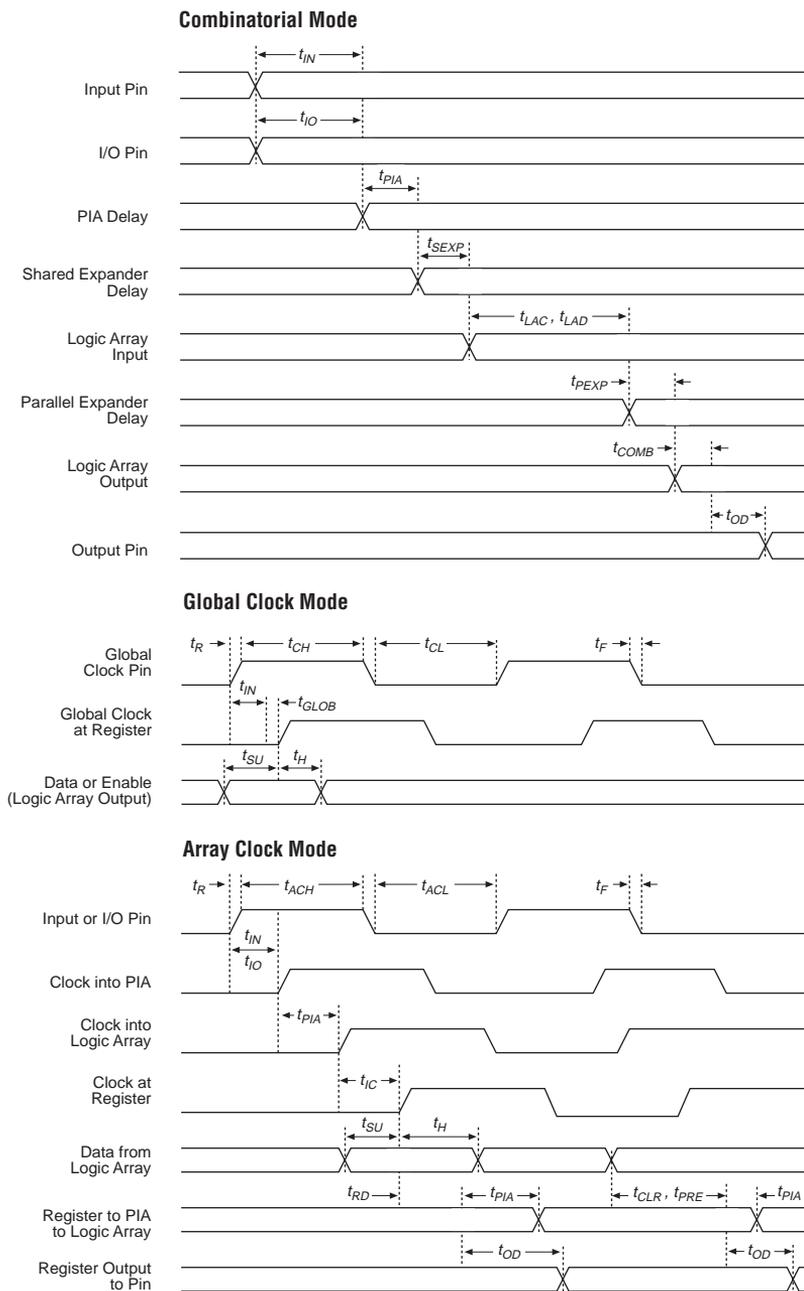
All MAX 7000A devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

## Generic Testing

MAX 7000A devices are fully tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in [Figure 9](#). Test patterns can be used and then erased during early stages of the production flow.

Figure 12. MAX 7000A Switching Waveforms

$t_R$  &  $t_F < 2$  ns. Inputs are driven at 3 V for a logic high and 0 V for a logic low. All timing characteristics are measured at 1.5 V.



Tables 17 through 30 show EPM7032AE, EPM7064AE, EPM7128AE, EPM7256AE, EPM7512AE, EPM7128A, and EPM7256A timing information.

**Table 17. EPM7032AE External Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{PD1}$	Input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10	ns
$t_{PD2}$	I/O input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10	ns
$t_{SU}$	Global clock setup time	(2)	2.9		4.7		6.3		ns
$t_H$	Global clock hold time	(2)	0.0		0.0		0.0		ns
$t_{FSU}$	Global clock setup time of fast input		2.5		3.0		3.0		ns
$t_{FH}$	Global clock hold time of fast input		0.0		0.0		0.0		ns
$t_{CO1}$	Global clock to output delay	C1 = 35 pF	1.0	3.0	1.0	5.0	1.0	6.7	ns
$t_{CH}$	Global clock high time		2.0		3.0		4.0		ns
$t_{CL}$	Global clock low time		2.0		3.0		4.0		ns
$t_{ASU}$	Array clock setup time	(2)	1.6		2.5		3.6		ns
$t_{AH}$	Array clock hold time	(2)	0.3		0.5		0.5		ns
$t_{ACO1}$	Array clock to output delay	C1 = 35 pF (2)	1.0	4.3	1.0	7.2	1.0	9.4	ns
$t_{ACH}$	Array clock high time		2.0		3.0		4.0		ns
$t_{ACL}$	Array clock low time		2.0		3.0		4.0		ns
$t_{CPPW}$	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
$t_{CNT}$	Minimum global clock period	(2)		4.4		7.2		9.7	ns
$f_{CNT}$	Maximum internal global clock frequency	(2), (4)	227.3		138.9		103.1		MHz
$t_{ACNT}$	Minimum array clock period	(2)		4.4		7.2		9.7	ns
$f_{ACNT}$	Maximum internal array clock frequency	(2), (4)	227.3		138.9		103.1		MHz

Table 18. EPM7032AE Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.7		1.2		1.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.7		1.2		1.5	ns
$t_{FIN}$	Fast input delay			2.3		2.8		3.4	ns
$t_{SEXP}$	Shared expander delay			1.9		3.1		4.0	ns
$t_{PEXP}$	Parallel expander delay			0.5		0.8		1.0	ns
$t_{LAD}$	Logic array delay			1.5		2.5		3.3	ns
$t_{LAC}$	Logic control array delay			0.6		1.0		1.2	ns
$t_{IOE}$	Internal output enable delay			0.0		0.0		0.0	ns
$t_{OD1}$	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		0.8		1.3		1.8	ns
$t_{OD2}$	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 2.5\text{ V}$	$C1 = 35\text{ pF}$ (5)		1.3		1.8		2.3	ns
$t_{OD3}$	Output buffer and pad delay, slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		5.8		6.3		6.8	ns
$t_{ZX1}$	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		4.0		4.0		5.0	ns
$t_{ZX2}$	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 2.5\text{ V}$	$C1 = 35\text{ pF}$ (5)		4.5		4.5		5.5	ns
$t_{ZX3}$	Output buffer enable delay, slow slew rate = on $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		4.0		4.0		5.0	ns
$t_{SU}$	Register setup time		1.3		2.0		2.8		ns
$t_H$	Register hold time		0.6		1.0		1.3		ns
$t_{FSU}$	Register setup time of fast input		1.0		1.5		1.5		ns
$t_{FH}$	Register hold time of fast input		1.5		1.5		1.5		ns
$t_{RD}$	Register delay			0.7		1.2		1.5	ns
$t_{COMB}$	Combinatorial delay			0.6		1.0		1.3	ns

Table 19. EPM7064AE External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{PD1}$	Input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10.0	ns
$t_{PD2}$	I/O input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10.0	ns
$t_{SU}$	Global clock setup time	(2)	2.8		4.7		6.2		ns
$t_H$	Global clock hold time	(2)	0.0		0.0		0.0		ns
$t_{FSU}$	Global clock setup time of fast input		2.5		3.0		3.0		ns
$t_{FH}$	Global clock hold time of fast input		0.0		0.0		0.0		ns
$t_{CO1}$	Global clock to output delay	C1 = 35 pF	1.0	3.1	1.0	5.1	1.0	7.0	ns
$t_{CH}$	Global clock high time		2.0		3.0		4.0		ns
$t_{CL}$	Global clock low time		2.0		3.0		4.0		ns
$t_{ASU}$	Array clock setup time	(2)	1.6		2.6		3.6		ns
$t_{AH}$	Array clock hold time	(2)	0.3		0.4		0.6		ns
$t_{ACO1}$	Array clock to output delay	C1 = 35 pF (2)	1.0	4.3	1.0	7.2	1.0	9.6	ns
$t_{ACH}$	Array clock high time		2.0		3.0		4.0		ns
$t_{ACL}$	Array clock low time		2.0		3.0		4.0		ns
$t_{CPPW}$	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
$t_{CNT}$	Minimum global clock period	(2)		4.5		7.4		10.0	ns
$f_{CNT}$	Maximum internal global clock frequency	(2), (4)	222.2		135.1		100.0		MHz
$t_{ACNT}$	Minimum array clock period	(2)		4.5		7.4		10.0	ns
$f_{ACNT}$	Maximum internal array clock frequency	(2), (4)	222.2		135.1		100.0		MHz

Table 22. EPM7128AE Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.7		1.0		1.4	ns
$t_{IO}$	I/O input pad and buffer delay			0.7		1.0		1.4	ns
$t_{FIN}$	Fast input delay			2.5		3.0		3.4	ns
$t_{SEXP}$	Shared expander delay			2.0		2.9		3.8	ns
$t_{PEXP}$	Parallel expander delay			0.4		0.7		0.9	ns
$t_{LAD}$	Logic array delay			1.6		2.4		3.1	ns
$t_{LAC}$	Logic control array delay			0.7		1.0		1.3	ns
$t_{IOE}$	Internal output enable delay			0.0		0.0		0.0	ns
$t_{OD1}$	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		0.8		1.2		1.6	ns
$t_{OD2}$	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 2.5\text{ V}$	$C1 = 35\text{ pF}$ (5)		1.3		1.7		2.1	ns
$t_{OD3}$	Output buffer and pad delay, slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		5.8		6.2		6.6	ns
$t_{ZX1}$	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		4.0		4.0		5.0	ns
$t_{ZX2}$	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 2.5\text{ V}$	$C1 = 35\text{ pF}$ (5)		4.5		4.5		5.5	ns
$t_{ZX3}$	Output buffer enable delay, slow slew rate = on $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		4.0		4.0		5.0	ns
$t_{SU}$	Register setup time		1.4		2.1		2.9		ns
$t_H$	Register hold time		0.6		1.0		1.3		ns
$t_{FSU}$	Register setup time of fast input		1.1		1.6		1.6		ns
$t_{FH}$	Register hold time of fast input		1.4		1.4		1.4		ns
$t_{RD}$	Register delay			0.8		1.2		1.6	ns
$t_{COMB}$	Combinatorial delay			0.5		0.9		1.3	ns
$t_{IC}$	Array clock delay			1.2		1.7		2.2	ns

Table 22. EPM7128AE Internal Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
$t_{EN}$	Register enable time			0.7		1.0		1.3	ns
$t_{GLOB}$	Global control delay			1.1		1.6		2.0	ns
$t_{PRE}$	Register preset time			1.4		2.0		2.7	ns
$t_{CLR}$	Register clear time			1.4		2.0		2.7	ns
$t_{PIA}$	PIA delay	(2)		1.4		2.0		2.6	ns
$t_{LPA}$	Low-power adder	(6)		4.0		4.0		5.0	ns

Table 25. EPM7512AE External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-12		
			Min	Max	Min	Max	Min	Max	
$t_{PD1}$	Input to non-registered output	C1 = 35 pF (2)		7.5		10.0		12.0	ns
$t_{PD2}$	I/O input to non-registered output	C1 = 35 pF (2)		7.5		10.0		12.0	ns
$t_{SU}$	Global clock setup time	(2)	5.6		7.6		9.1		ns
$t_H$	Global clock hold time	(2)	0.0		0.0		0.0		ns
$t_{FSU}$	Global clock setup time of fast input		3.0		3.0		3.0		ns
$t_{FH}$	Global clock hold time of fast input		0.0		0.0		0.0		ns
$t_{CO1}$	Global clock to output delay	C1 = 35 pF	1.0	4.7	1.0	6.3	1.0	7.5	ns
$t_{CH}$	Global clock high time		3.0		4.0		5.0		ns
$t_{CL}$	Global clock low time		3.0		4.0		5.0		ns
$t_{ASU}$	Array clock setup time	(2)	2.5		3.5		4.1		ns
$t_{AH}$	Array clock hold time	(2)	0.2		0.3		0.4		ns
$t_{ACO1}$	Array clock to output delay	C1 = 35 pF (2)	1.0	7.8	1.0	10.4	1.0	12.5	ns
$t_{ACH}$	Array clock high time		3.0		4.0		5.0		ns
$t_{ACL}$	Array clock low time		3.0		4.0		5.0		ns
$t_{CPPW}$	Minimum pulse width for clear and preset	(3)	3.0		4.0		5.0		ns
$t_{CNT}$	Minimum global clock period	(2)		8.6		11.5		13.9	ns
$f_{CNT}$	Maximum internal global clock frequency	(2), (4)	116.3		87.0		71.9		MHz
$t_{ACNT}$	Minimum array clock period	(2)		8.6		11.5		13.9	ns
$f_{ACNT}$	Maximum internal array clock frequency	(2), (4)	116.3		87.0		71.9		MHz

Table 26. EPM7512AE Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-12		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.7		0.9		1.0	ns
$t_{IO}$	I/O input pad and buffer delay			0.7		0.9		1.0	ns
$t_{FIN}$	Fast input delay			3.1		3.6		4.1	ns
$t_{SEXP}$	Shared expander delay			2.7		3.5		4.4	ns
$t_{PEXP}$	Parallel expander delay			0.4		0.5		0.6	ns
$t_{LAD}$	Logic array delay			2.2		2.8		3.5	ns
$t_{LAC}$	Logic control array delay			1.0		1.3		1.7	ns
$t_{IOE}$	Internal output enable delay			0.0		0.0		0.0	ns
$t_{OD1}$	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		1.0		1.5		1.7	ns
$t_{OD2}$	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 2.5\text{ V}$	$C1 = 35\text{ pF}$ (5)		1.5		2.0		2.2	ns
$t_{OD3}$	Output buffer and pad delay, slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$		6.0		6.5		6.7	ns
$t_{ZX1}$	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		4.0		5.0		5.0	ns
$t_{ZX2}$	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 2.5\text{ V}$	$C1 = 35\text{ pF}$ (5)		4.5		5.5		5.5	ns
$t_{ZX3}$	Output buffer enable delay, slow slew rate = on $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		9.0		10.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		4.0		5.0		5.0	ns
$t_{SU}$	Register setup time		2.1		3.0		3.5		ns
$t_H$	Register hold time		0.6		0.8		1.0		ns
$t_{FSU}$	Register setup time of fast input		1.6		1.6		1.6		ns
$t_{FH}$	Register hold time of fast input		1.4		1.4		1.4		ns
$t_{RD}$	Register delay			1.3		1.7		2.1	ns
$t_{COMB}$	Combinatorial delay			0.6		0.8		1.0	ns

**Table 26. EPM7512AE Internal Timing Parameters (Part 2 of 2)** *Note (1)*

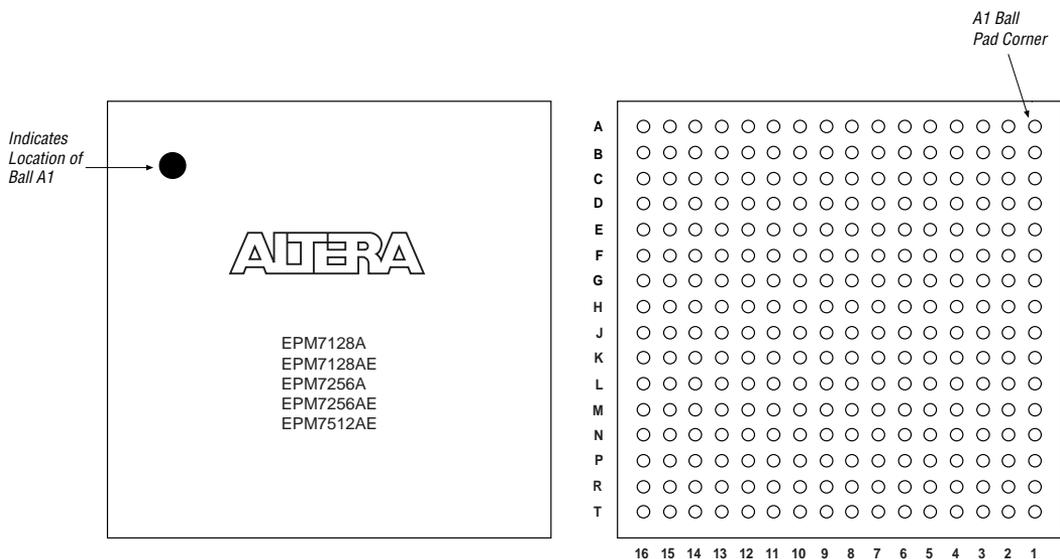
Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-12		
			Min	Max	Min	Max	Min	Max	
$t_{IC}$	Array clock delay			1.8		2.3		2.9	ns
$t_{EN}$	Register enable time			1.0		1.3		1.7	ns
$t_{GLOB}$	Global control delay			1.7		2.2		2.7	ns
$t_{PRE}$	Register preset time			1.0		1.4		1.7	ns
$t_{CLR}$	Register clear time			1.0		1.4		1.7	ns
$t_{PIA}$	PIA delay	(2)		3.0		4.0		4.8	ns
$t_{LPA}$	Low-power adder	(6)		4.5		5.0		5.0	ns

Table 27. EPM7128A External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-12		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{PD1}$	Input to non-registered output	C1 = 35 pF (2)		6.0		7.5		10.0		12.0	ns
$t_{PD2}$	I/O input to non-registered output	C1 = 35 pF (2)		6.0		7.5		10.0		12.0	ns
$t_{SU}$	Global clock setup time	(2)	4.2		5.3		7.0		8.5		ns
$t_{H}$	Global clock hold time	(2)	0.0		0.0		0.0		0.0		ns
$t_{FSU}$	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
$t_{FH}$	Global clock hold time of fast input		0.0		0.0		0.0		0.0		ns
$t_{CO1}$	Global clock to output delay	C1 = 35 pF	1.0	3.7	1.0	4.6	1.0	6.1	1.0	7.3	ns
$t_{CH}$	Global clock high time		3.0		3.0		4.0		5.0		ns
$t_{CL}$	Global clock low time		3.0		3.0		4.0		5.0		ns
$t_{ASU}$	Array clock setup time	(2)	1.9		2.4		3.1		3.8		ns
$t_{AH}$	Array clock hold time	(2)	1.5		2.2		3.3		4.3		ns
$t_{ACO1}$	Array clock to output delay	C1 = 35 pF (2)	1.0	6.0	1.0	7.5	1.0	10.0	1.0	12.0	ns
$t_{ACH}$	Array clock high time		3.0		3.0		4.0		5.0		ns
$t_{ACL}$	Array clock low time		3.0		3.0		4.0		5.0		ns
$t_{CPPW}$	Minimum pulse width for clear and preset	(3)	3.0		3.0		4.0		5.0		ns
$t_{CNT}$	Minimum global clock period	(2)		6.9		8.6		11.5		13.8	ns
$f_{CNT}$	Maximum internal global clock frequency	(2), (4)	144.9		116.3		87.0		72.5		MHz
$t_{ACNT}$	Minimum array clock period	(2)		6.9		8.6		11.5		13.8	ns
$f_{ACNT}$	Maximum internal array clock frequency	(2), (4)	144.9		116.3		87		72.5		MHz

Figure 23. 256-Pin FineLine BGA Package Pin-Out Diagram

Package outline not drawn to scale.



## Revision History

The information contained in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.5 supersedes information published in previous versions.

### Version 4.5

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.5:

- Updated text in the “Power Sequencing & Hot-Socketing” section.

### Version 4.4

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.4:

- Added Tables 5 through 7.
- Added “Programming Sequence” on page 17 and “Programming Times” on page 18.